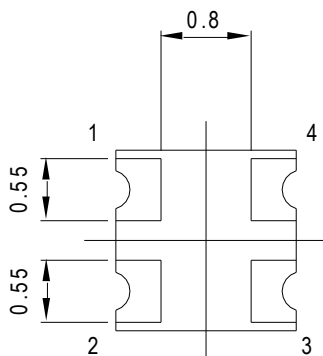
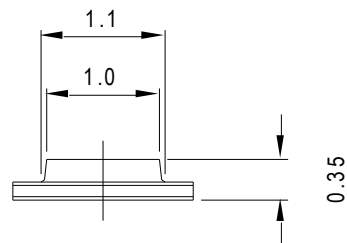
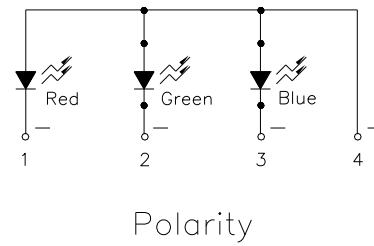
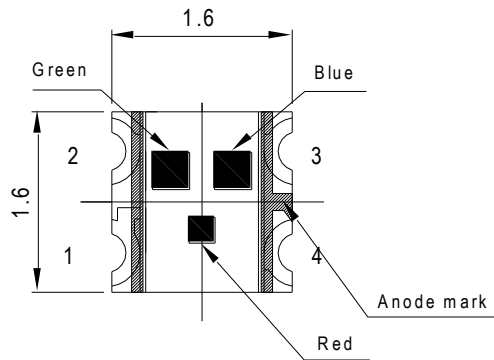
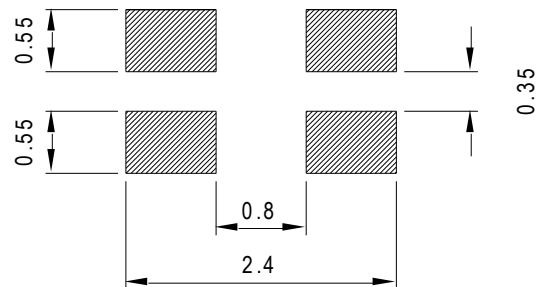


Package Outline Dimensions



For reflow soldering (propose)



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	R6:25 GH:25 BH:25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	R6:60 GH:100 BH:100	mA
Power Dissipation	P _d	R6:60 GH:95 BH:95	mW
Electrostatic Discharge(HBM)	ESD	R6:2000 GH:150 BH:150	V
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +90	°C
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	R6 I _v	18		45		I _F =5mA
	GH	57	-----	140	mcd	
	BH	14.5		36		
Viewing Angle	2θ 1/2	-----	120	-----	deg	
Peak Wavelength	R6 λ _p		632			
	GH	-----	518	-----	nm	
	BH		468			
Dominant Wavelength	R6 λ _d	618		628		I _F =5mA
	GH	520	-----	535	nm	
	BH	465		475		
Spectrum Radiation Bandwidth	R6 Δλ		20			
	GH	-----	35	-----	nm	
	BH		25			
Forward Voltage	R6 V _F	1.7		2.1		I _F =5mA
	GH	2.6	-----	3.0	V	
	BH	2.6		3.0		
Reverse Current	R6 I _R			10		V _R =5V
	GH	-----	-----	50	μA	
	BH			50		

Notes:

- 1.Tolerance of Luminous Intensity ±11%
- 2.Tolerance of Dominant Wavelength ±1nm
- 3.Tolerance of Forward Voltage ±0.05V

R6

Bin Range Of Luminous Intensity

Bin	Min	Max	Unit	Condition
M	18.0	28.5	mcd	If=5mA
N	28.5	45.0		

GH

Bin Range Of Luminous Intensity

Bin	Min	Max	Unit	Condition
PA	57.0	90.0	mcd	If=5mA
QA	90.0	140.0		

Bin Range Of Dom. Wavelength

Bin	Min	Max	Unit	Condition
X	520	525	nm	If=5mA
Y	525	530		
Z	530	535		

BH

Bin Range Of Luminous Intensity

Bin	Min	Max	Unit	Condition
LA	14.5	22.5	mcd	If=5mA
MA	22.5	36.0		

Bin Range Of Dom. Wavelength

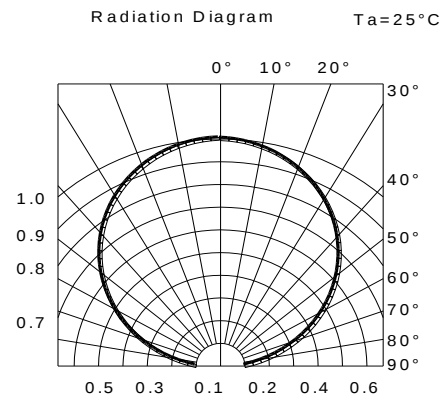
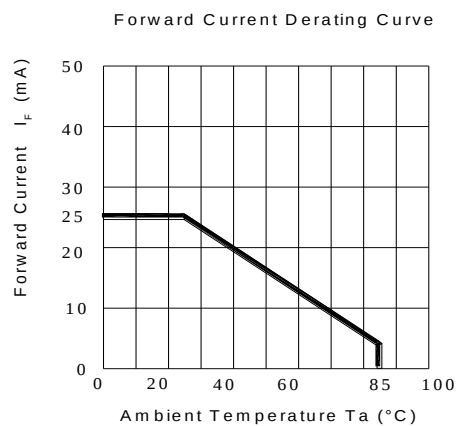
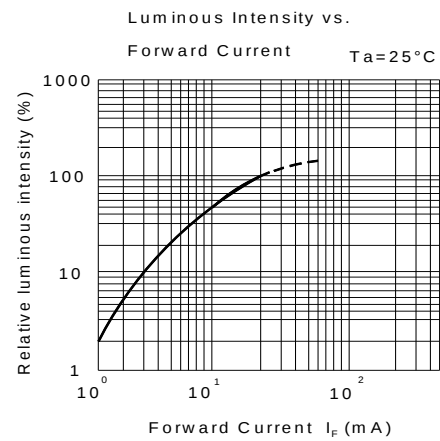
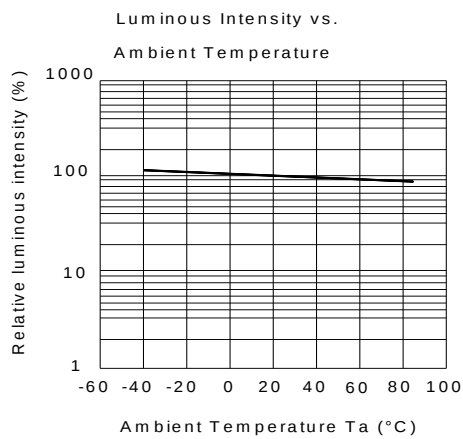
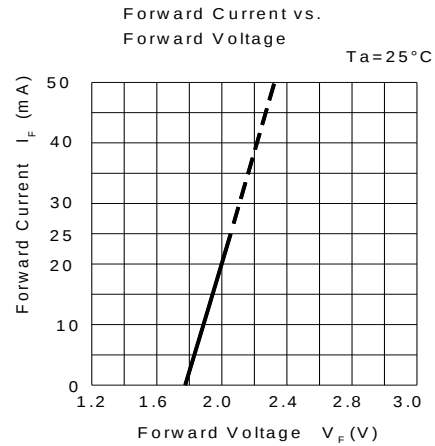
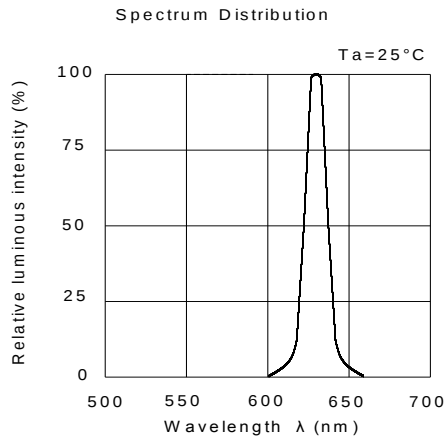
Bin	Min	Max	Unit	Condition
X	465	470	nm	If=5mA
Y	470	475		

Notes:

- 1.Tolerance of Luminous Intensity $\pm 11\%$
- 2.Tolerance of Dominant Wavelength $\pm 1\text{nm}$

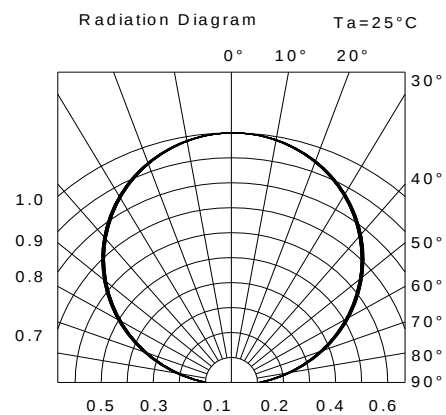
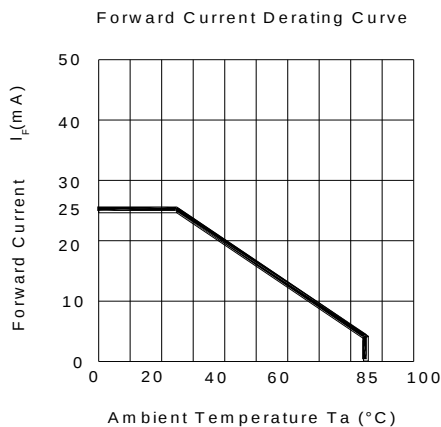
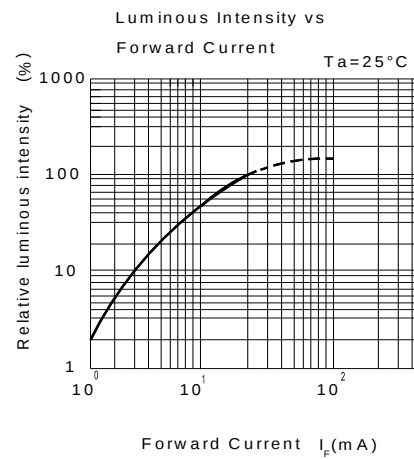
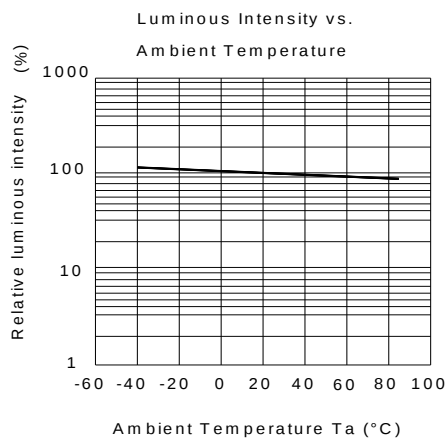
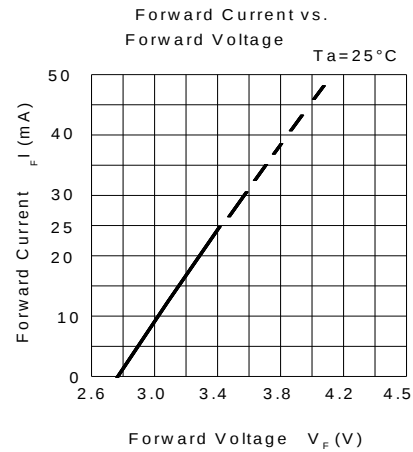
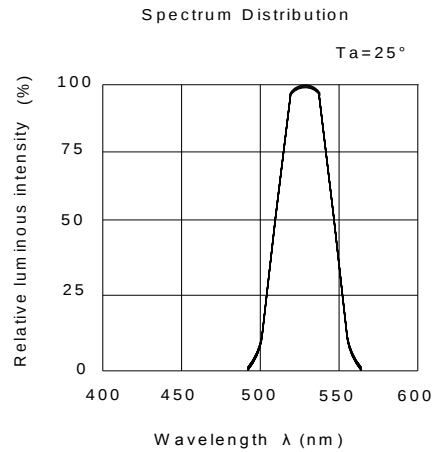
Typical Electro-Optical Characteristics Curves

R6



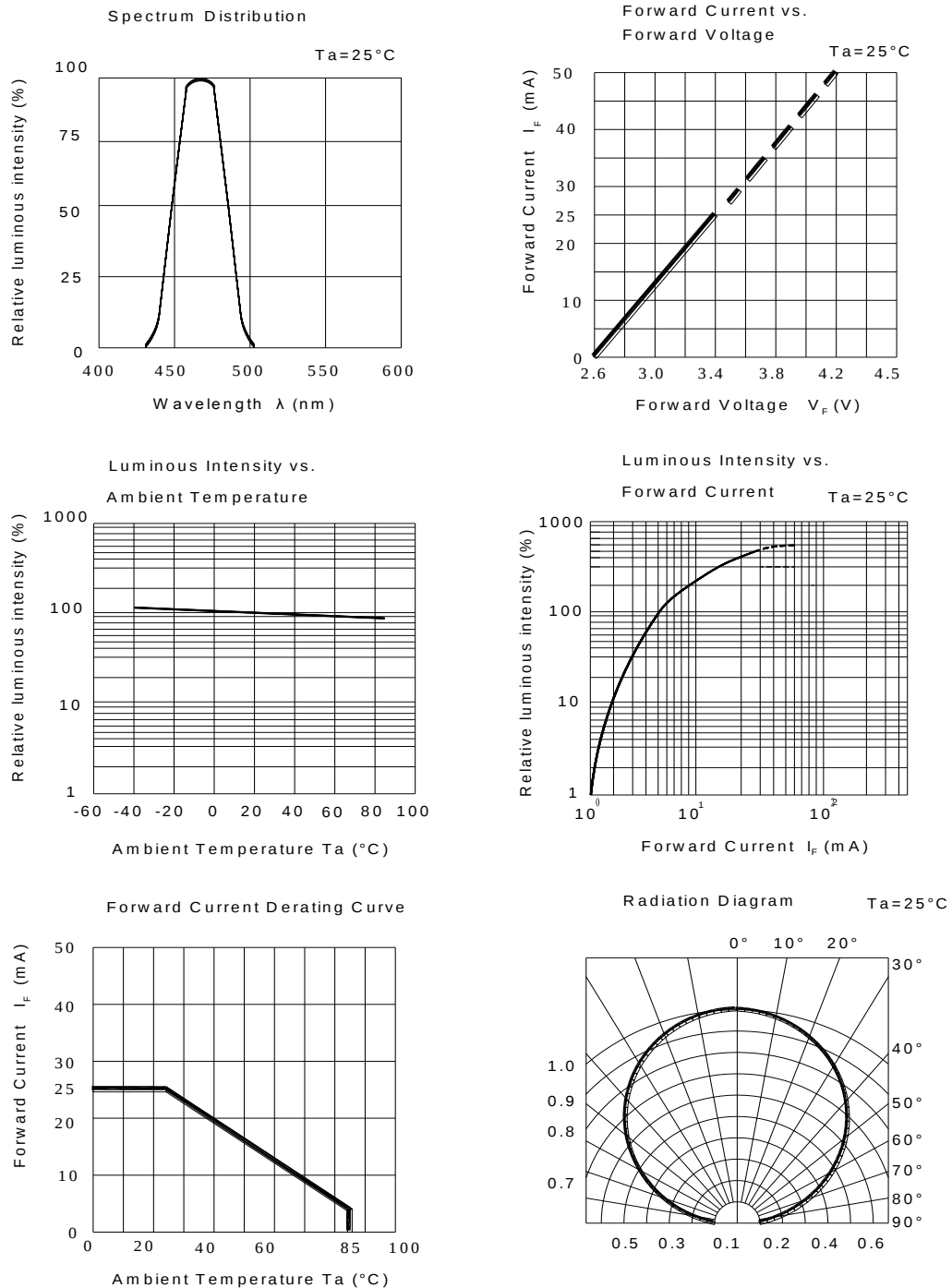
Typical Electro-Optical Characteristics Curves

GH



Typical Electro-Optical Characteristics Curves

BH



Label Explanation

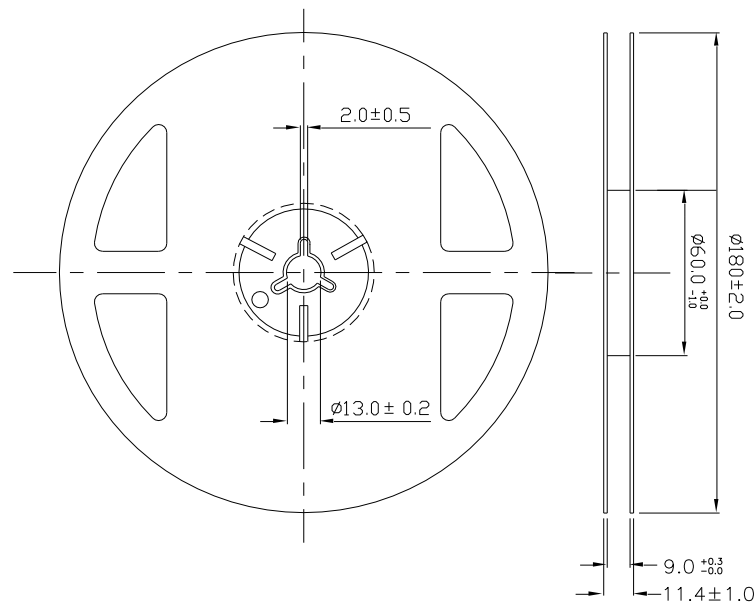
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank

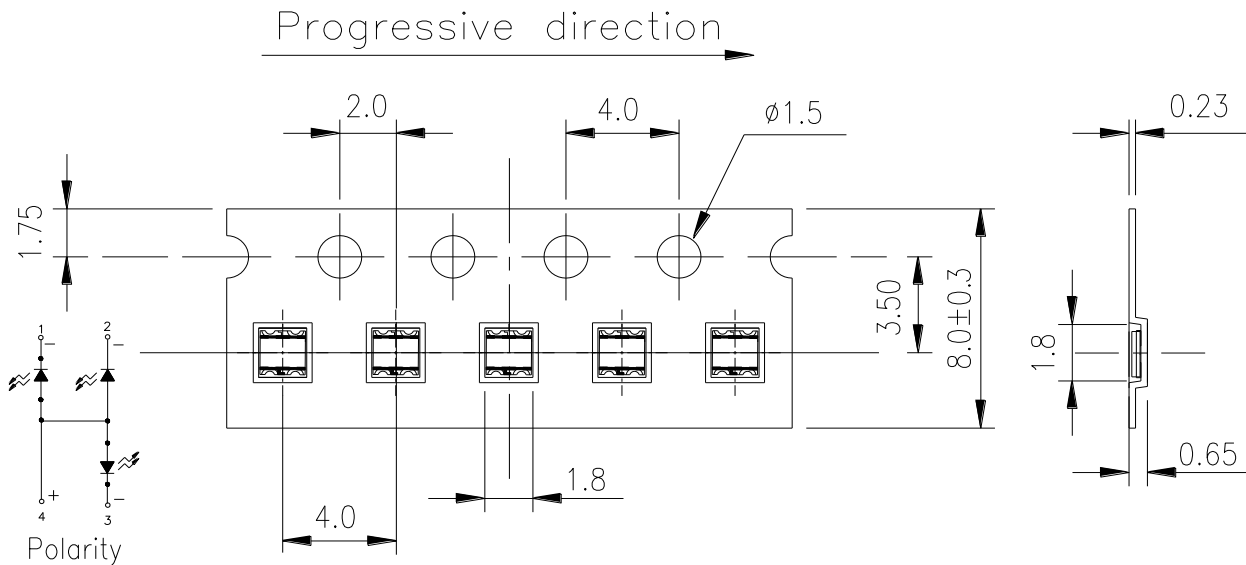


Reel Dimensions



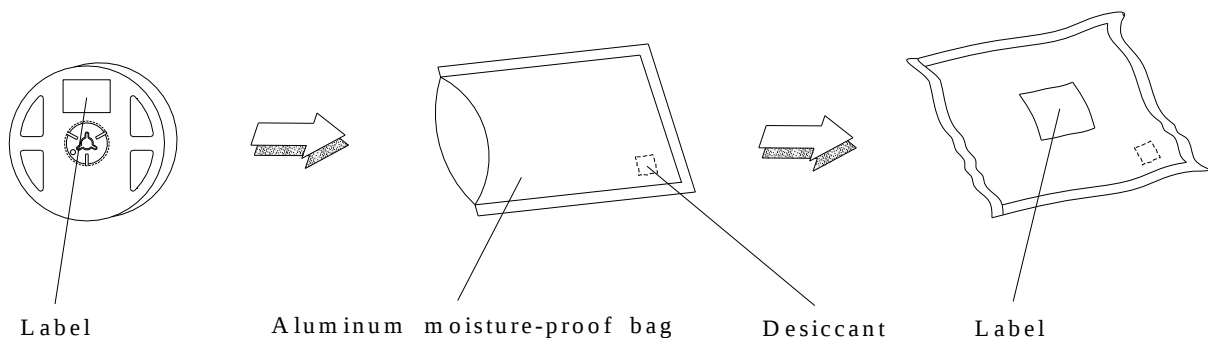
Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Carrier Tape Dimensions: Loaded quantity 2000 PCS per reel



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Moisture Resistant Packaging



Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Max. 10sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I _F = 20 mA	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C / 85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less.

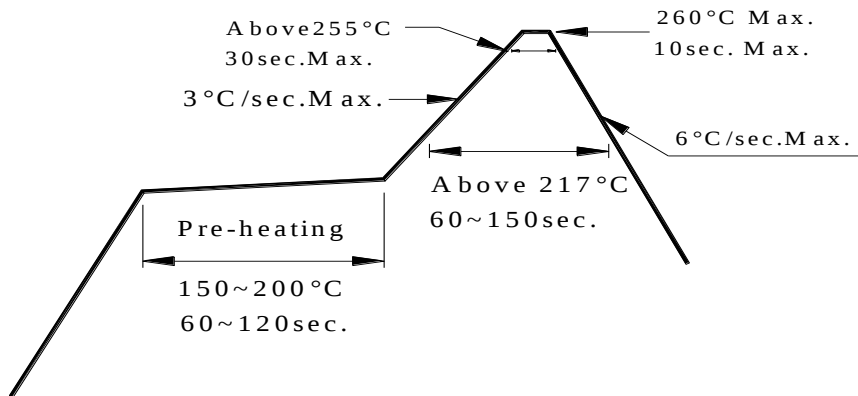
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

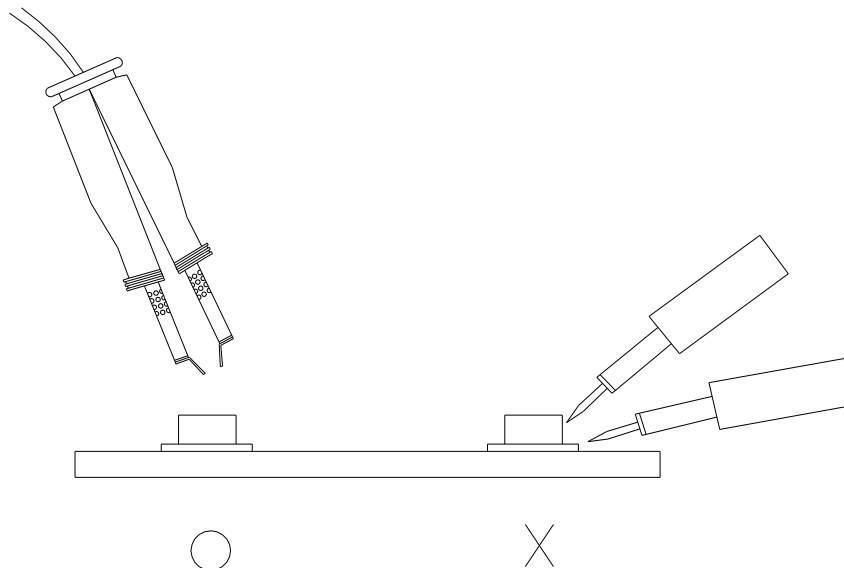
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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